

the process chamber and/or the substrate temperature, characterized by a pump (10) for pumping out the process chamber between the individual process steps and a device for purging the process chamber with inert gas in a purging operation between the process steps, and a residual gas analyzer for analyzing the exhaust-gas pumped out of the process chamber (6) for residual constituents of the starting material and/or for solvent and for interrupting the purging operation when the residual gas concentration drops below a minimum value.

3. (Currently Amended) Process or apparatus according to claim 1 ~~one or more of the preceding claims or in particular according thereto~~, characterized in that the walls of the process chamber are or can be controlled to different temperatures.

4. (Currently Amended) Process according to claim 1 ~~one of the preceding claims~~, characterized in that in the first process step a metalorganic starting material, which may optionally have been dissolved in a solvent, is converted into the gas phase and is introduced into the process chamber (6), if appropriate together with the solvent, by means of a showerhead-like gas inlet member (7), and the gas inlet member (7) and the process chamber (6) are purged with inert gas (5) after the supply of this starting material has been switched off.

5. (Currently Amended) Process according to claim 4, characterized in that in the second process step a dielectric layer is deposited on the metal layer, as a result of a perovskite, which has optionally been dissolved in a solvent, as starting material being converted into the gas phase and being introduced into the process chamber (6), if appropriate together with the solvent, by means of the showerhead-like gas inlet member (7), and the gas inlet member (7) and the process chamber (6) being purged with an inert gas (5) after the supply of this starting material has been switched off, the exhaust-gas which has been pumped out of the process chamber (6) being analyzed, in particular by mass spectrometry, for residual constituents of the starting material, and the purging operation being terminated only when the

residual gas concentration, in particular the oxygen concentration, drops below a minimum value.

6. (Currently Amended) The process as claimed in claim 5, characterized in that in a third process step a metal layer is deposited on a dielectric layer which has previously been deposited, a metalorganic starting material, which has optionally been dissolved in a solvent, being converted into the gas form and being introduced into the process chamber (6), if appropriate together with the solvent, by means of the showerhead-like gas inlet member (7), and the gas inlet member (7) and the process chamber (6) being purged with an inert gas (5) after the supply of this starting material has been switched off, the exhaust-gas which is pumped out of the process chamber (6) being analyzed, in particular by mass spectrometry, for residual constituents of the starting material and/or the solvent, and the purging operation being terminated only when the residual gas concentration drops below a minimum value.

7. (Currently Amended) Process according to claim 6 ~~one or more of the preceding claims or in particular according thereto~~, characterized in that the purging of the process chamber (6) with the inert gas (5) is associated with one or more pressure changes.

8. (Currently Amended) Process according to claim 7 ~~one or more of the preceding claims or in particular according thereto~~, characterized in that the first metal layer is a platinum layer.

9. (Currently Amended) Process according to claim 8 ~~one or more of the preceding claims or in particular according thereto~~, characterized in that the dielectric layer consists of a barium-strontium-titanium-oxygen compound.

Page 4

Applicant: Markus Schumacher  
Preliminary Amendment

10. (Currently Amended) Process according to claim 9 ~~one or more of the preceding claims or in particular according thereto~~, characterized in that the second metal layer is a ruthenium layer.